

MA27E02

Silicon epitaxial planar type

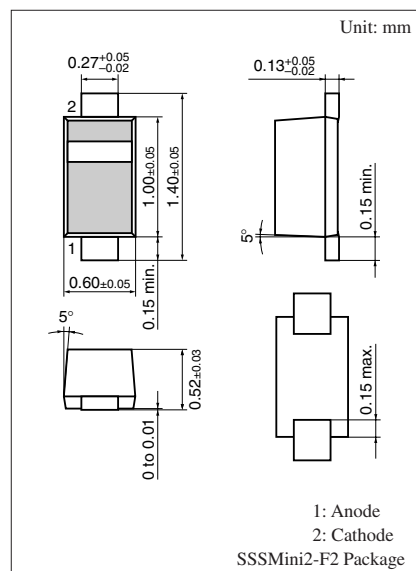
For cellular phone

■ Features

- High-frequency wave detection is possible.
- Low forward voltage V_F
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Maximum peak reverse voltage	V_{RM}	20	V
Forward current	I_F	35	mA
Peak forward current	I_{FM}	100	mA
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



Marking Symbol: G

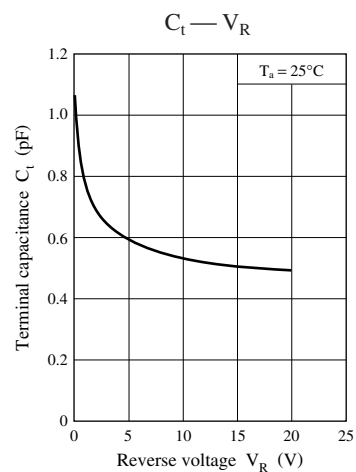
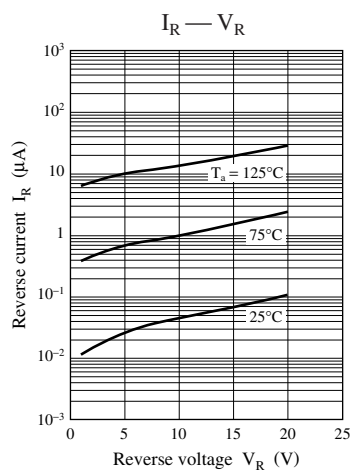
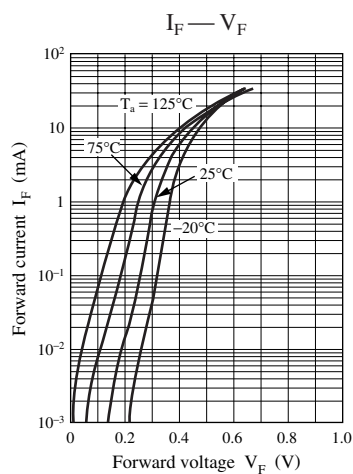
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.40	V
	V_{F2}	$I_F = 35 \text{ mA}$			1.0	V
Reverse current	I_R	$V_R = 15 \text{ V}$			200	nA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			1.2	pF
Forward dynamic resistance	r_f	$I_F = 5 \text{ mA}$		9		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Rated input/output frequency: 2 GHz



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